

SOT1878-1

plastic, thermal enhanced super thin quad flat package; no leads; 20 terminals; 0.4 mm pitch, 3.0 mm x 2.0 mm x 0.35 mm body

1 June 2018

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HX2QFN20
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	10-6-2016
Manufacturer package code	SOT1878-1

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.95	2	2.05	mm
package width	2.95	3	3.05	mm
seated height	0.3	0.35	0.4	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	20	-	A/A

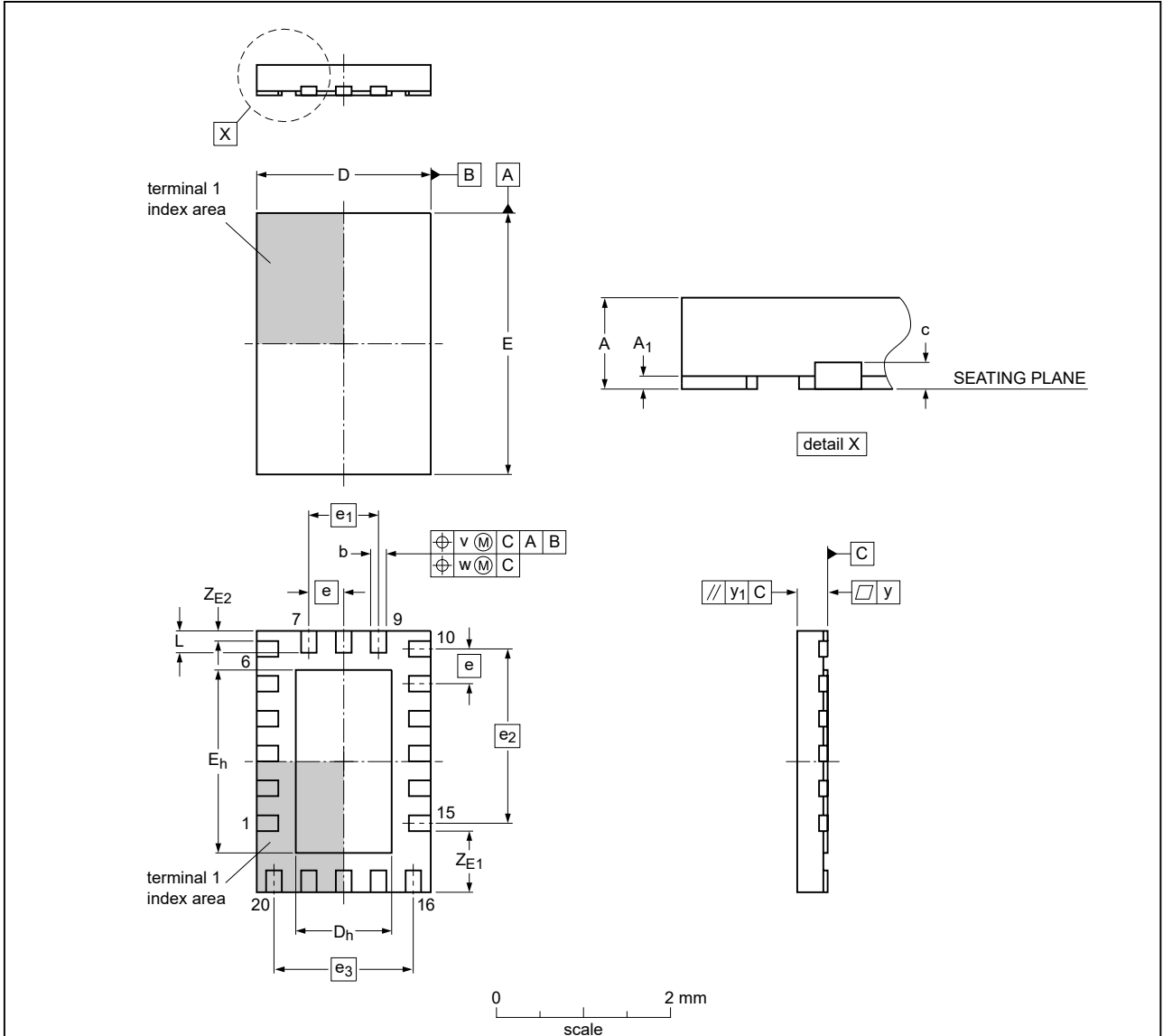


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2. Package outline

HX2QFN20: plastic, thermal enhanced super thin quad flat package; no leads; 20 terminals; body 3.0 x 2.0 x 0.35 mm

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Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	e ₂	e ₃	L	Z _{E1}	Z _{E2}	v	w	y	y ₁
max	0.40	0.08	0.23		2.05	1.20	3.05	2.20					0.30						
mm nom	0.35	0.05	0.18	0.10	2.00	1.10	3.00	2.10	0.4	0.8	2.0	1.6	0.25	0.703	0.118	0.07	0.05	0.05	0.1
min	0.30	0.00	0.13		1.95	1.00	2.95	2.00					0.20						

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1878-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1878-1		---			16-04-26 16-05-09

Fig. 1. Package outline SOT1878-1

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3. Legal information

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